

ABSTRACT

A method of plating a metal layer over isolated pads on a semiconductor package substrate is proposed. This substrate is formed with a plurality of conductive blind vias. The isolated pads are formed on a surface of the substrate, each having a plating line extending towards one blind via but electrically insulated from the blind via by an electrically insulating region. A conductive film covers the surface of the substrate having the isolated pads, and a photoresist layer is formed over the conductive film. The photoresist layer has openings for exposing a portion of the conductive film covering the isolated pads. The exposed portion of the conductive film is removed, to allow a metal layer to be plated on the isolated pads. Then, the photoresist layer and the remainder of the conductive film are removed, and the electrical insulation between the isolated pads and the blind vias is restored.

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